



CY8C21512-12PVXET Status: In Production

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CY8C21512-12PVXET

Development Kit	CY3213A-DK
LCD Direct Drive	N
PWMs	HW
CPU Core	M8C
Max. Operating Frequency (MHz)	12
Automotive Qualified	Y
CapSense	Y
Min. Operating Voltage (V)	3.00
Max. Operating Voltage (V)	5.25
Min. Operating Temp. (°C)	-40
Max. Operating Temp. (°C)	125
No. of Dedicated Comparators	0
No. of GPIOs	24
No. of Programmable Digital Blocks	1
SRAM (KB)	0.5
No. of CapSense IO	20
Proximity Sensing	Y
Sliders	4
SmartSense Enabled	N
Comm. Interface	I2C, SPI, UART
Flash (KB)	8

Pricing & Inventory Availability

1-10 unit Price*	11-100 unit Price*	101-1000 unit Price*	1001 + unit Price*

Availability	Quantity	Ships In	Order Now

* Prices are shown in United States dollars and are for budgetary use only.

Packaging / Ordering

Package	SSOP
No. of Pins	28
Package Dimensions	408 L X 0 H X 210 W (Mils)
Package Weight	229.90 (mgs)

Package Cross Section Drawing	Download
Package Carrier	REEL
Package Carrier Drawing / Orientation	Tape Drawing , Reel Drawing , Package Orientation
Standard Pack Quantity	1000
Minimum Order Quantity (MOQ)	1000
Order Increment	1000
Estimated Lead Time (days)	56
HTS Code	8542.31.0000
ECCN	EAR99

Quality and RoHS

Moisture Sensitivity Level (MSL)	3
Peak Reflow Temp. (°C)	260 (Cypress Reflow Profile)
RoHS Compliant	Y Print RoHS Certificate of Compliance
PB Free	Y
Lead/Ball Finish	Ni/Pd/Au
Marking	Cypress Marking Format

Package Material Declaration

[28L-SSOP PB-FREE PACKAGE MATERIAL DECLARATION DATASHEET \(PMDD\)](#) Last Update: 07/16/2012

IPC 1752 Material Declaration

[IPC-1752-2_V1.1_SSOP 28_CML_NIPDAU](#) Last Update: 07/05/2012

[IPC-1752-2_V1.1_SSOP 28_OSET_PURE SN](#) Last Update: 07/04/2012

RoHS Analysis Certificates (CoA)

[PACKAGE ROHS ANALYSIS REPORT - SSOP \(SP 20, 28\) USING MOLD COMPOUND CEL9220HF, ADHESIVE 8340, PURE SN - OSE TAIWAN ASSEMBLY](#) Last Update: 07/04/2012

[PACKAGE ROHS ANALYSIS REPORT - SSOP \(SP20,28,48,56\) QSOP \(SQ20,24\) SOIC \(SZ18,24\) TSOP \(ZT32\) USING MOLD COMPOUND KEG3000DA, ADHESIVE QMI509, NIPDAU - CML ASSEMBLY](#) Last Update: 07/04/2012

Device Qualification Reports

 FIT/MTBF, ESD (HBM/CDM) and Latch-up data available in the Device Qualification Report. Please click [here](#).

Technical Documents

Application Notes (27)

[AN2397 - CapSense® Data Viewing Tools](#) Last Update: 04/04/2013

[AN78646 - Integrated Power Manager using PSoC® 1](#) Last Update: 18/03/2013

[AN73212 - Debugging with PSoC® 1](#) Last Update: 20/02/2013

[AN17310 - PSoC® 1 Power Savings Using Sleep Mode](#) Last Update: 04/02/2013

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Product Information Notice (PIN) (1)

[PIN135200](#) Last Update: 21/03/2013

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